

Multilayer Ceramic Chip Capacitors

C2012CH2W272K125AA



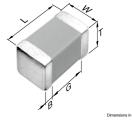






TDK item description C2012CH2W272KT****

Applications	Commercial Grade	
Feature	Mid Voltage (100 to 630V)	
Series	C2012 [EIA 0805]	
Status	Production (Not Recommended for New Design)	



	Size	
Length(L)	2.00mm ±0.20mm	
Width(W)	1.25mm ±0.20mm	
Thickness(T)	1.25mm ±0.20mm	
Terminal Width(B)	0.20mm Min.	
Terminal Spacing(G)		
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering)	
recommended Land Fattern (FA)	0.90mm to 1.20mm(Reflow Soldering)	
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering)	
recommended Land Fattern (FB)	0.70mm to 0.90mm(Reflow Soldering)	
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering)	
Recommended Land Fattern (FC)	0.90mm to 1.20mm(Reflow Soldering)	

Electrical Characteristics		
Capacitance	2.7nF ±10%	
Rated Voltage	450VDC	
Temperature Characteristic	CH(0±60ppm/°C)	
Q (Min.)	1000	
Insulation Resistance (Min.)	10000ΜΩ	

Other	
Coldoring Mathod	Wave (Flow)
Soldering Method	Reflow
AEC-Q200	No
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	2000pcs

[!] Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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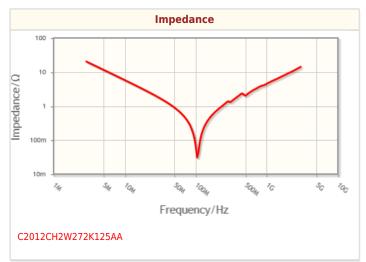


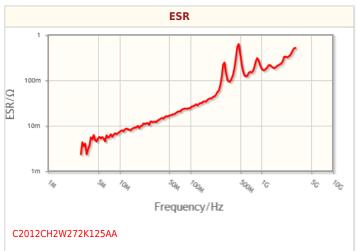


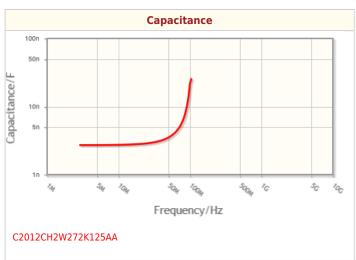


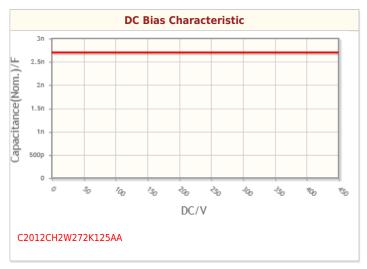


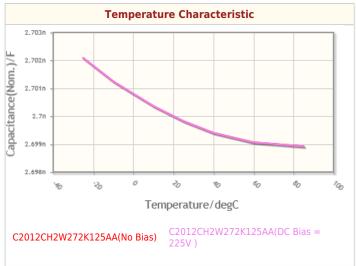
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)











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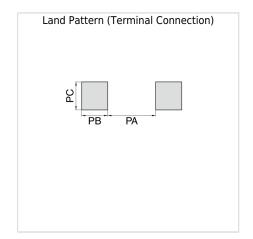








Associated Images



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